

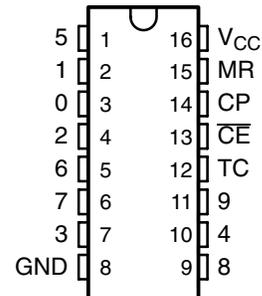
CD74HC4017-Q1

HIGH-SPEED CMOS LOGIC DECADE COUNTER/DIVIDER WITH 10 DECODED OUTPUTS

SCLS546SA – OCTOBER 2003 – REVISED APRIL 2008

- Qualified for Automotive Applications
- Fully Static Operation
- Buffered Inputs
- Common Reset
- Positive Edge Clocking
- Typical $f_{MAX} = 60$ MHz at $V_{CC} = 5$ V, $C_L = 15$ pF, $T_A = 25^\circ\text{C}$
- Fanout (Over Temperature Range)
 - Standard Outputs . . . 10 LSTTL Loads
 - Bus Driver Outputs . . . 15 LSTTL Loads
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- V_{CC} Voltage = 2 V to 6 V
- High Noise Immunity N_{IL} or $N_{IH} = 30\%$ of V_{CC} , $V_{CC} = 5$ V

M OR PW PACKAGE
(TOP VIEW)



description/ordering information

The CD74HC4017 is a high-speed silicon-gate CMOS 5-stage Johnson counter with ten decoded outputs. Each of the decoded outputs normally is low and sequentially goes high on the low-to-high transition clock period of the ten-clock-period cycle. The carry (TC) output transitions low to high after output 9 goes from high to low, and can be used in conjunction with the clock enable (\overline{CE}) input to cascade several stages. \overline{CE} disables counting when in the high state. A master reset (MR) input also is provided that, when taken high, sets all the decoded outputs, except output 0, to low.

The device can drive up to ten low-power Schottky equivalent loads.

ORDERING INFORMATION†

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – M	Tape and reel	CD74HC4017QM96Q1	HC4017Q
	TSSOP – PW	Tape and reel	CD74HC4017QPWRQ1	HC4017Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

FUNCTION TABLE

INPUTS			OUTPUT STATE†
CP	\overline{CE}	MR	
L	X	L	No change
X	H	L	No change
X	X	H	0 = H, 1–9 = L
↑	L	L	Increments counter
↓	X	L	No change
X	↑	L	No change
H	↓	L	Increments counter

NOTE: H = high voltage level, L = low voltage level,
X = don't care, ↑ = transition from low to high level, ↓ = transition from high to low level

† If $n < 5$, TC = H, otherwise TC = L



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



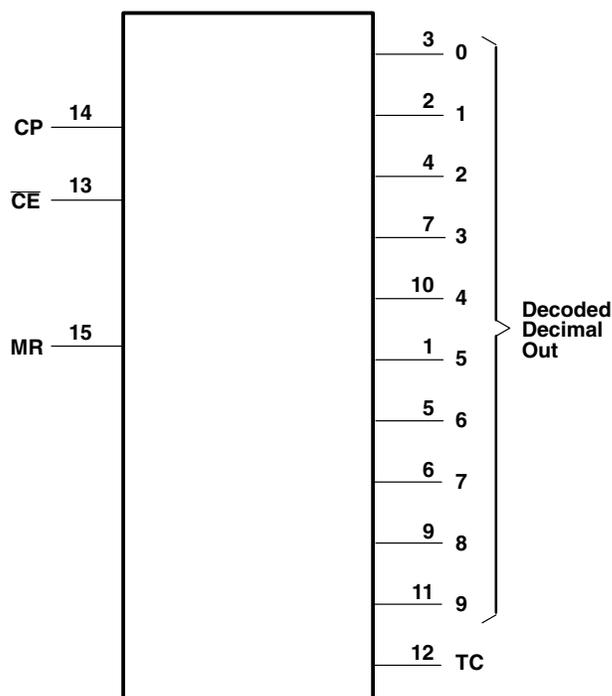
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1)	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	± 20 mA
Output clamp current, I_{OK} ($V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)	± 20 mA
Source or sink current per output pin, I_O ($V_O > -0.5$ V or $V_O < V_{CC} + 0.5$ V)	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2): M package	73°C/W
	PW package	108°C/W
Maximum junction temperature, T_J	150°C
Lead temperature (during soldering):		
At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10 s max	300°C
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages referenced to GND unless otherwise specified.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage	2	6	V	
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5	V	
		V _{CC} = 4.5 V	3.15		
		V _{CC} = 6 V	4.2		
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5	V	
		V _{CC} = 4.5 V	1.35		
		V _{CC} = 6 V	1.8		
V _I	Input voltage	0	V _{CC}	V	
V _O	Output voltage	0	V _{CC}	V	
t _i	Input transition (rise and fall) time	V _{CC} = 2 V	0	1000	ns
		V _{CC} = 4.5 V	0	500	
		V _{CC} = 6 V	0	400	
T _A	Operating free-air temperature	-40	125	°C	

NOTES: 3. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	I _O (mA)	V _{CC}	T _A = 25°C		MIN	MAX	UNIT
				MIN	MAX			
V _{OH}	V _I = V _{IH} or V _{IL}	CMOS loads	-0.02	2 V	1.9	1.9	V	
			-0.02	4.5 V	4.4	4.4		
			-0.02	6 V	5.9	5.9		
		TTL loads	-4	4.5 V	3.98	3.7		
			-5.2	6 V	5.48	5.2		
V _{OL}	V _I = V _{IH} or V _{IL}	CMOS loads	0.02	2 V	0.1	0.1	V	
			0.02	4.5 V	0.1	0.1		
			0.02	6 V	0.1	0.1		
		TTL loads	4	4.5 V	0.26	0.4		
			5.2	6 V	0.26	0.4		
I _I	V _I = V _{CC} or GND		6 V	±0.1	±1	μA		
I _{CC}	V _I = V _{CC} or GND	0	6 V	8	160	μA		
C _{IN}	C _L = 50 pF			10	10	pF		



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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER			V _{CC}	T _A = 25°C		MIN	MAX	UNIT
				MIN	MAX			
f _{max}	Maximum clock frequency		2 V	6		4		MHz
			4.5 V	30		20		
			6 V	35		23		
t _w	Pulse duration	CP	2 V	80		120		ns
			4.5 V	16		24		
			6 V	14		20		
		MR	2 V	80		120		
			4.5 V	16		24		
			6 V	14		20		
t _{su}	Setup time	CE to CP	2 V	75		110		ns
			4.5 V	15		22		
			6 V	13		19		
		MR inactive	2 V	5		5		
			4.5 V	5		5		
			6 V	5		5		
t _h	Hold time, CE to CP		2 V	0		0		ns
			4.5 V	0		0		
			6 V	0		0		



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V _{CC}	T _A = 25°C			MIN	MAX	UNIT	
					MIN	TYP	MAX				
t _{pd}	CP	Decade out	C _L = 50 pF	2 V		230		345	ns		
				4.5 V		46	69				
				6 V		39	59				
			C _L = 15 pF	5 V	19						
				TC	C _L = 50 pF	2 V		230			345
						4.5 V		46		69	
		6 V				39	59				
		C _L = 15 pF	5 V		19						
			Decade out		C _L = 50 pF	2 V		250			375
						4.5 V		50		75	
		6 V				43	64				
		C _L = 15 pF		5 V	21						
	TC			C _L = 50 pF	2 V		250			375	
					4.5 V		50	75			
		6 V			43	64					
		C _L = 15 pF	5 V	21							
			MR	Decade out	C _L = 50 pF	2 V		230			345
						4.5 V		46		69	
	6 V					39	59				
	C _L = 15 pF	5 V			19						
		TC			C _L = 50 pF	2 V		230			345
						4.5 V		46		69	
	6 V					39	59				
	C _L = 15 pF			5 V	19						
TC, Decade out				C _L = 50 pF	2 V		75		110		
					4.5 V		15	22			
	6 V				13	19					
f _{max}	CP			C _L = 15 pF	5 V	60			MHz		

operating characteristics, V_{CC} = 5 V, T_A = 25°C, input t_r, t_f = 6 ns, C_L = 15 pF

PARAMETER	TYP	UNIT
C _{pd} Power dissipation capacitance (see Note 4)	39	pF

NOTE 4: C_{pd} is used to determine the dynamic power consumption per package.

$$P_D = (C_{pd} \times V_{CC}^2 \times f_i) + \Sigma(C_L \times V_{CC}^2 \times f_o)$$

f_i = input frequency

f_o = output frequency

C_L = output load capacitance

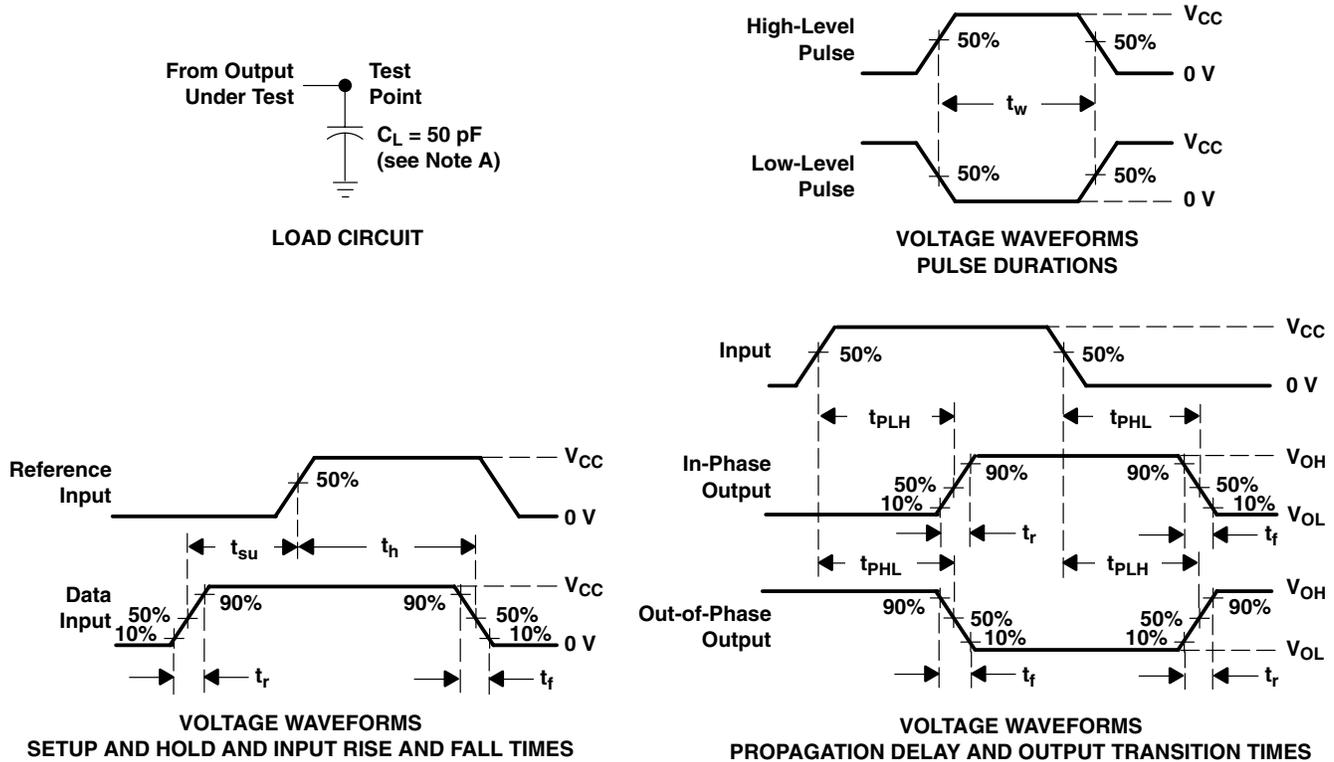
V_{CC} = supply voltage



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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 - C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. t_{pLH} and t_{pHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD74HC4017QM96G4Q1	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		HC4017Q	Samples
CD74HC4017QM96Q1	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 125	HC4017Q	
CD74HC4017QPWRG4Q1	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC4017Q	Samples
CD74HC4017QPWRQ1	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI	-40 to 125	HC4017Q	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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OTHER QUALIFIED VERSIONS OF CD74HC4017-Q1 :

- Catalog: [CD74HC4017](#)
- Enhanced Product: [CD74HC4017-EP](#)
- Military: [CD54HC4017](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



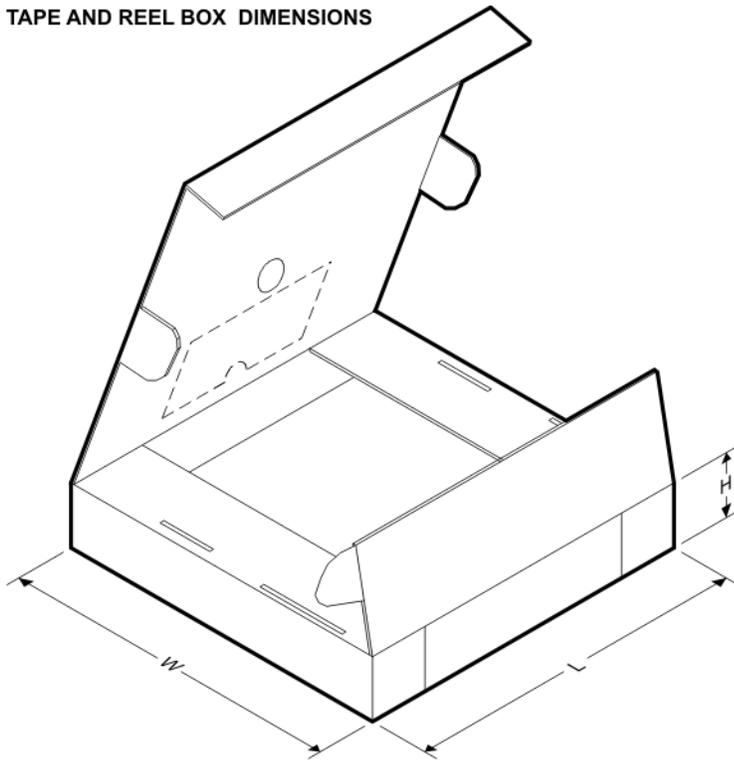
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4017QPWRG4Q 1	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

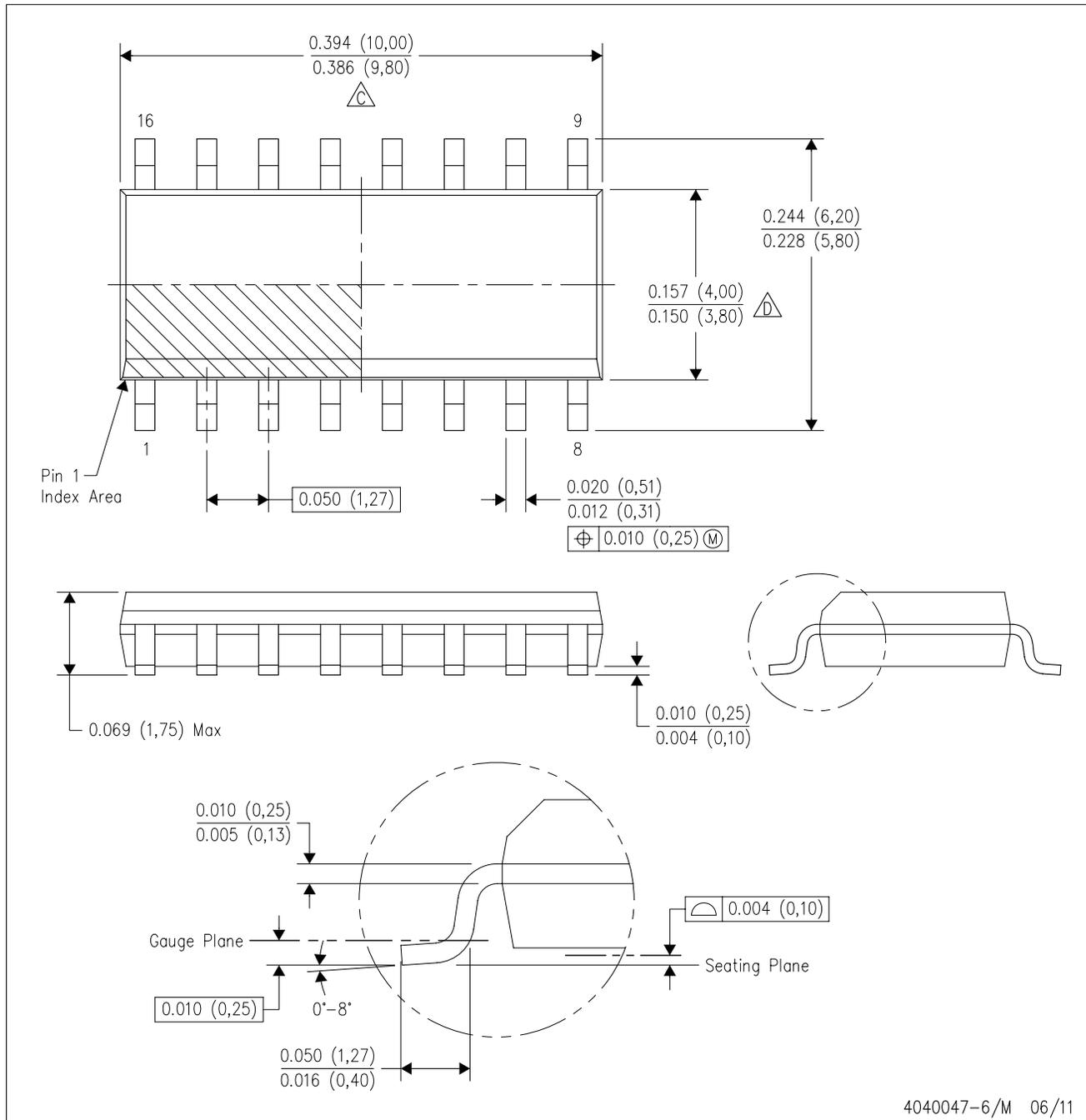


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4017QPWRG4Q1	TSSOP	PW	16	2000	367.0	367.0	35.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

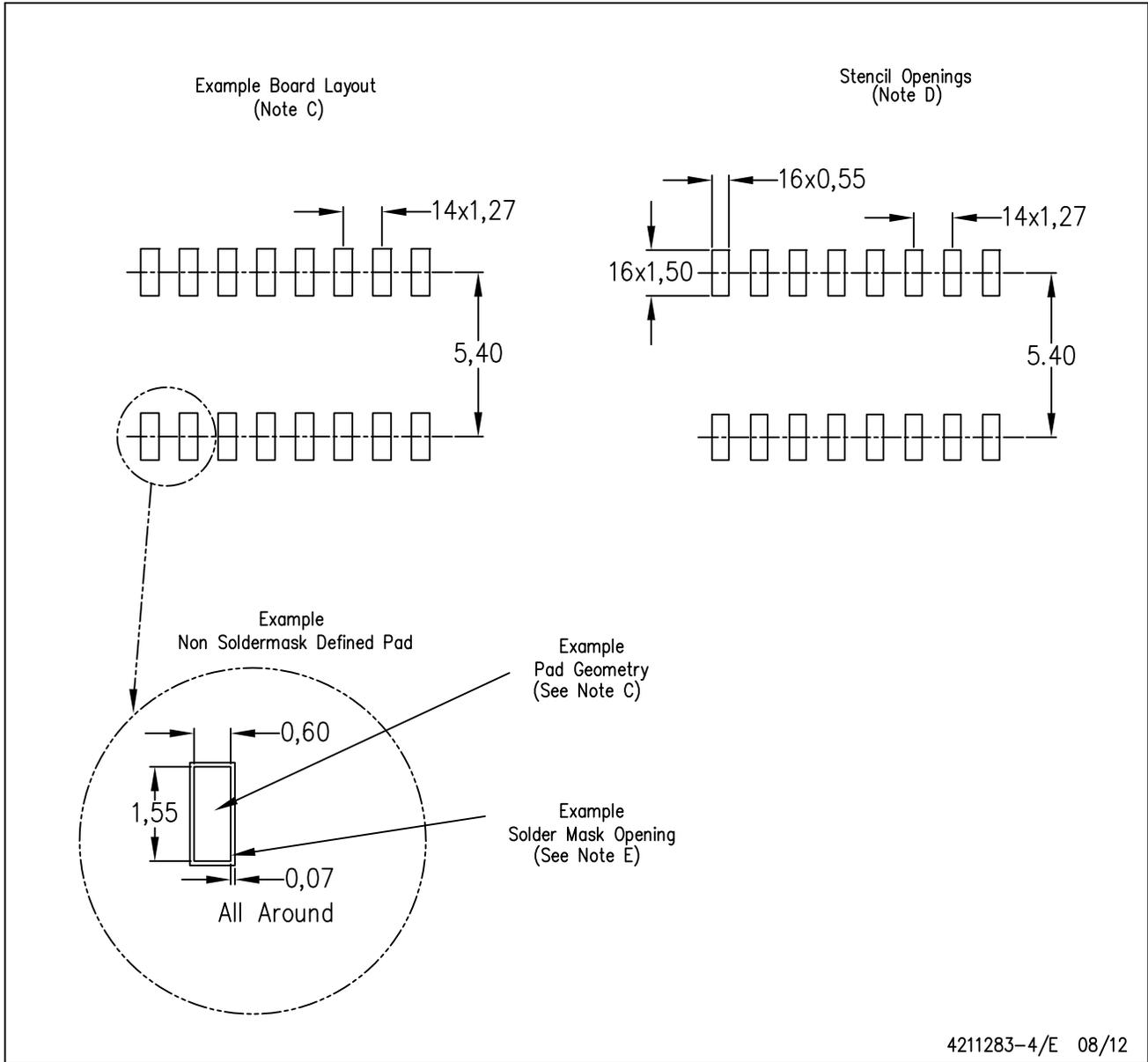


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- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

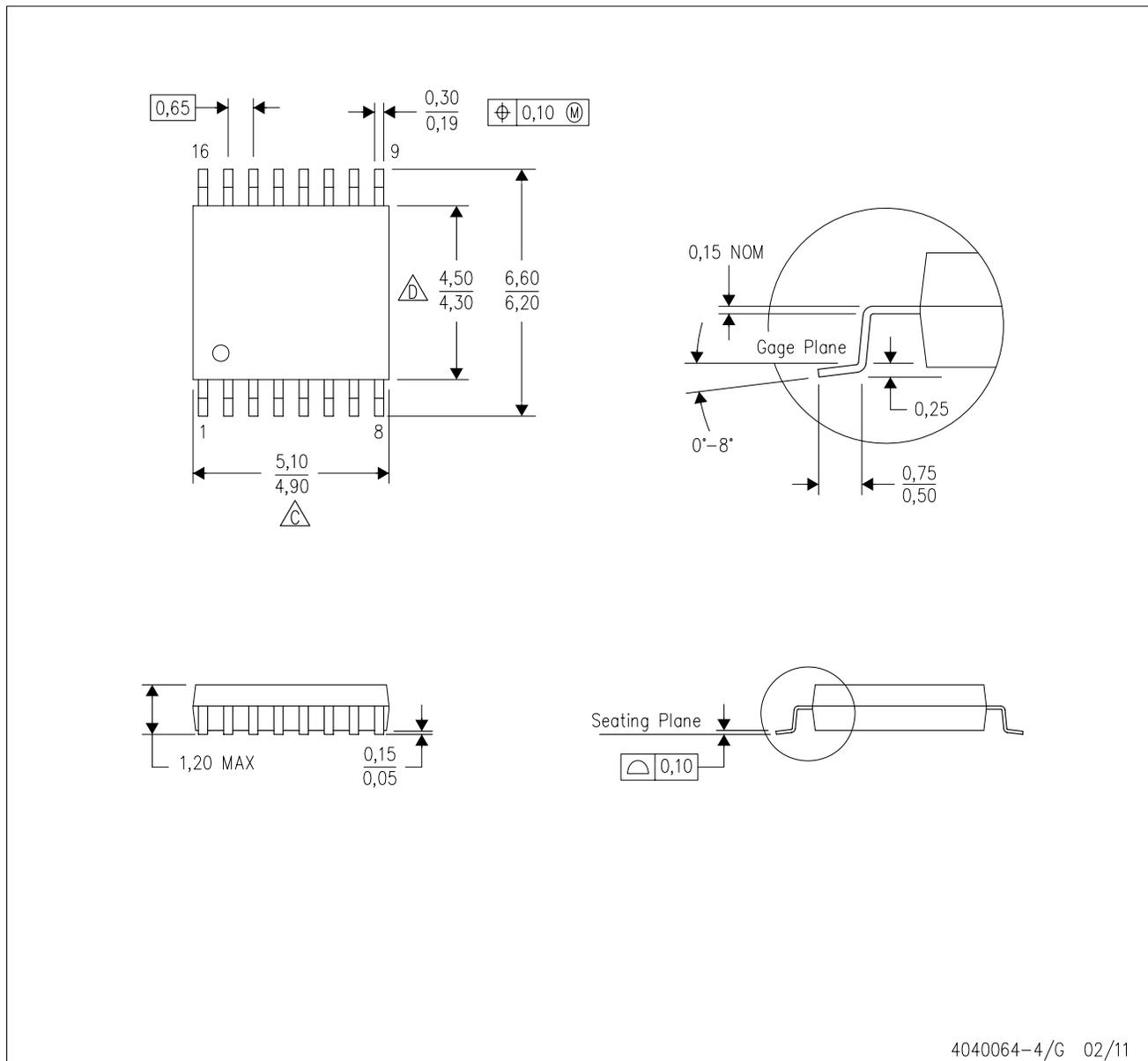
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

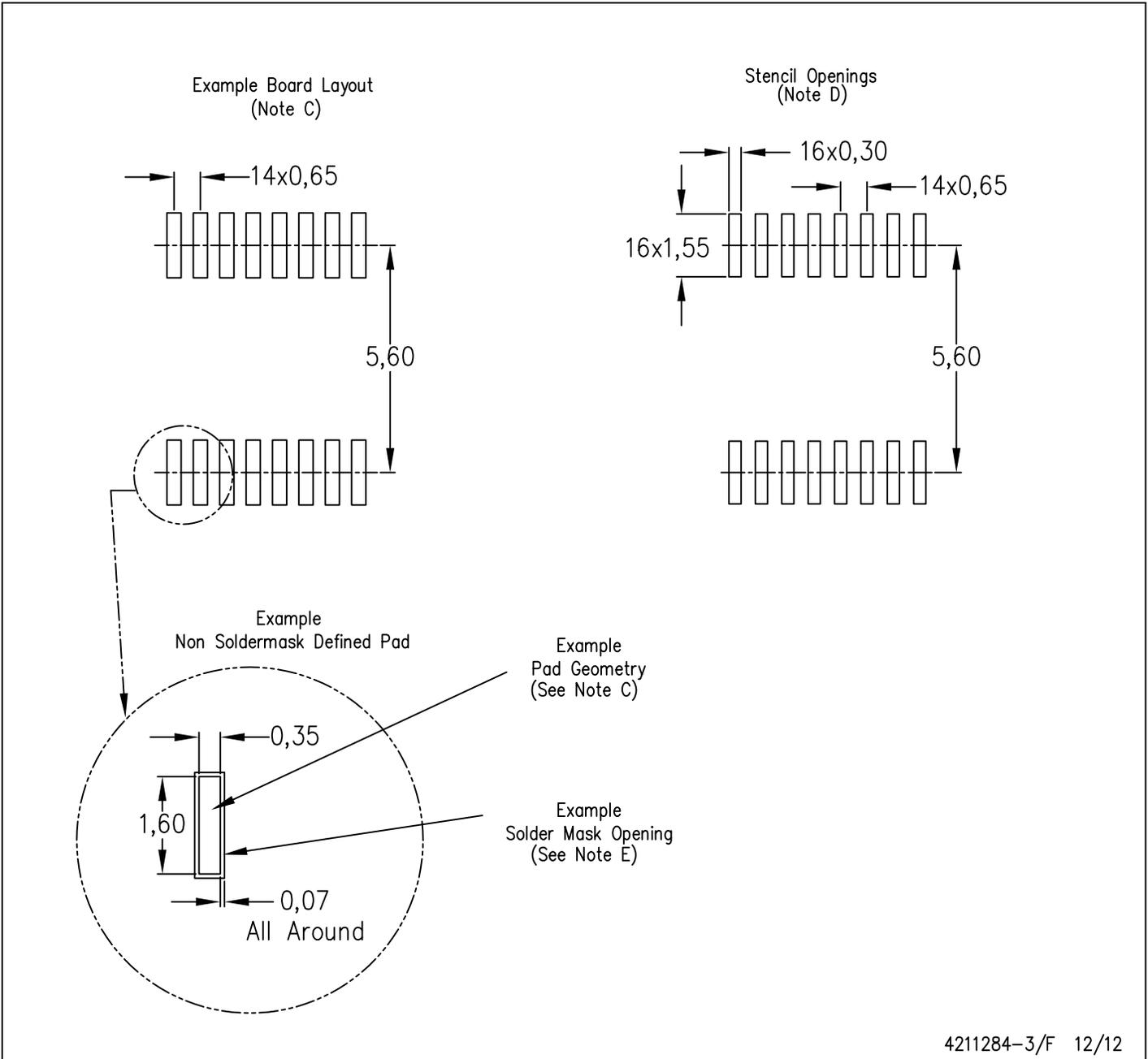
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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